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What is "Embedded - Microcontrollers"?

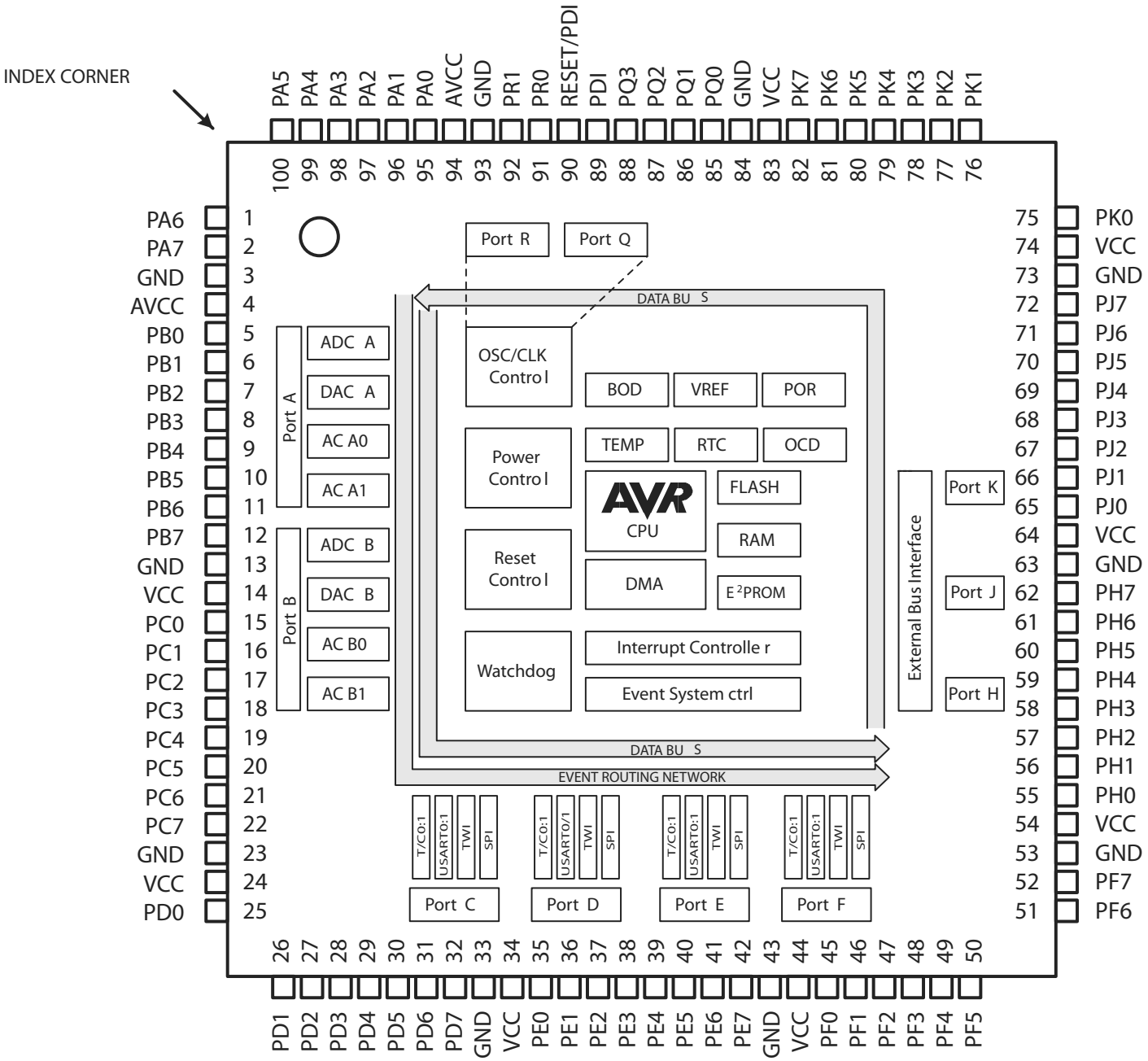
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8/16-Bit
Speed	32MHz
Connectivity	EBI/EMI, I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	78
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 16x12b; D/A 4x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-CBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atxmega128a1-cu

2. Pinout/Block Diagram

Figure 2-1. Block diagram and pinout



Notes: 1. For full details on pinout and pin functions refer to “Pinout and Pin Functions” on page 55.

2. VCC/GND on pin 83/84 are swapped compared to other VCC/GND to allow easier routing of GND to 32kHz crystal.

Figure 2-2. CBGA-pinout

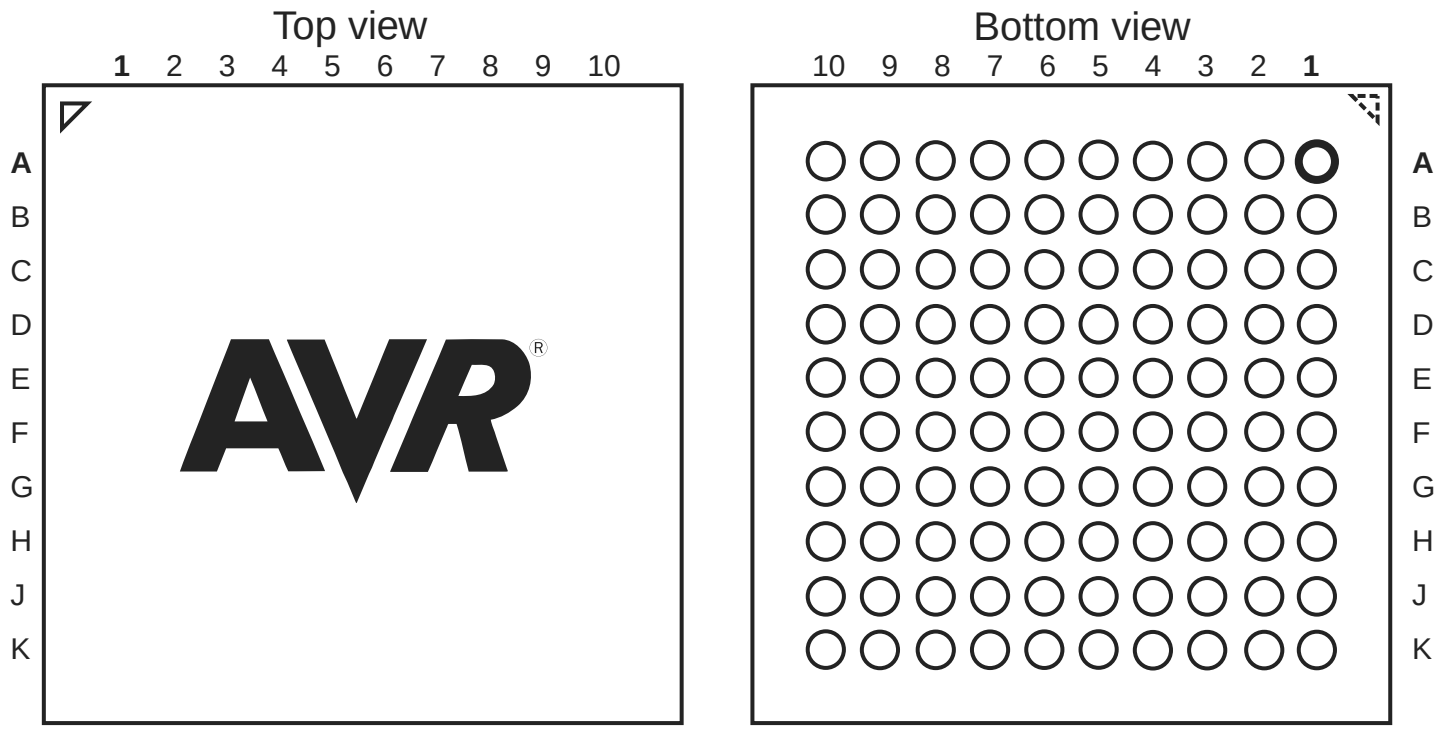


Table 2-1. CBGA-pinout.

	1	2	3	4	5	6	7	8	9	10
A	PK0	VCC	GND	PJ3	VCC	GND	PH1	GND	VCC	PF7
B	PK3	PK2	PK1	PJ4	PH7	PH4	PH2	PH0	PF6	PF5
C	VCC	PK5	PK4	PJ5	PJ0	PH5	PH3	PF2	PF3	VCC
D	GND	PK6	PK7	PJ6	PJ1	PH6	PF0	PF1	PF4	GND
E	PQ0	PQ1	PQ2	PJ7	PJ2	PE7	PE6	PE5	PE4	PE3
F	PR1	PR0	RESET/ PDI	PDI	PQ3	PC2	PE2	PE1	PE0	VCC
G	GND	PA1	PA4	PB3	PB4	PC1	PC6	PD7	PD6	GND
H	AVCC	PA2	PA5	PB2	PB5	PC0	PC5	PD5	PD4	PD3
J	PA0	PA3	PB0	PB1	PB6	PC3	PC4	PC7	PD2	PD1
K	PA6	PA7	GND	AVCC	PB7	VCC	GND	VCC	GND	PD0

3.1 Block Diagram

Figure 3-1. XMEGA A1 Block Diagram

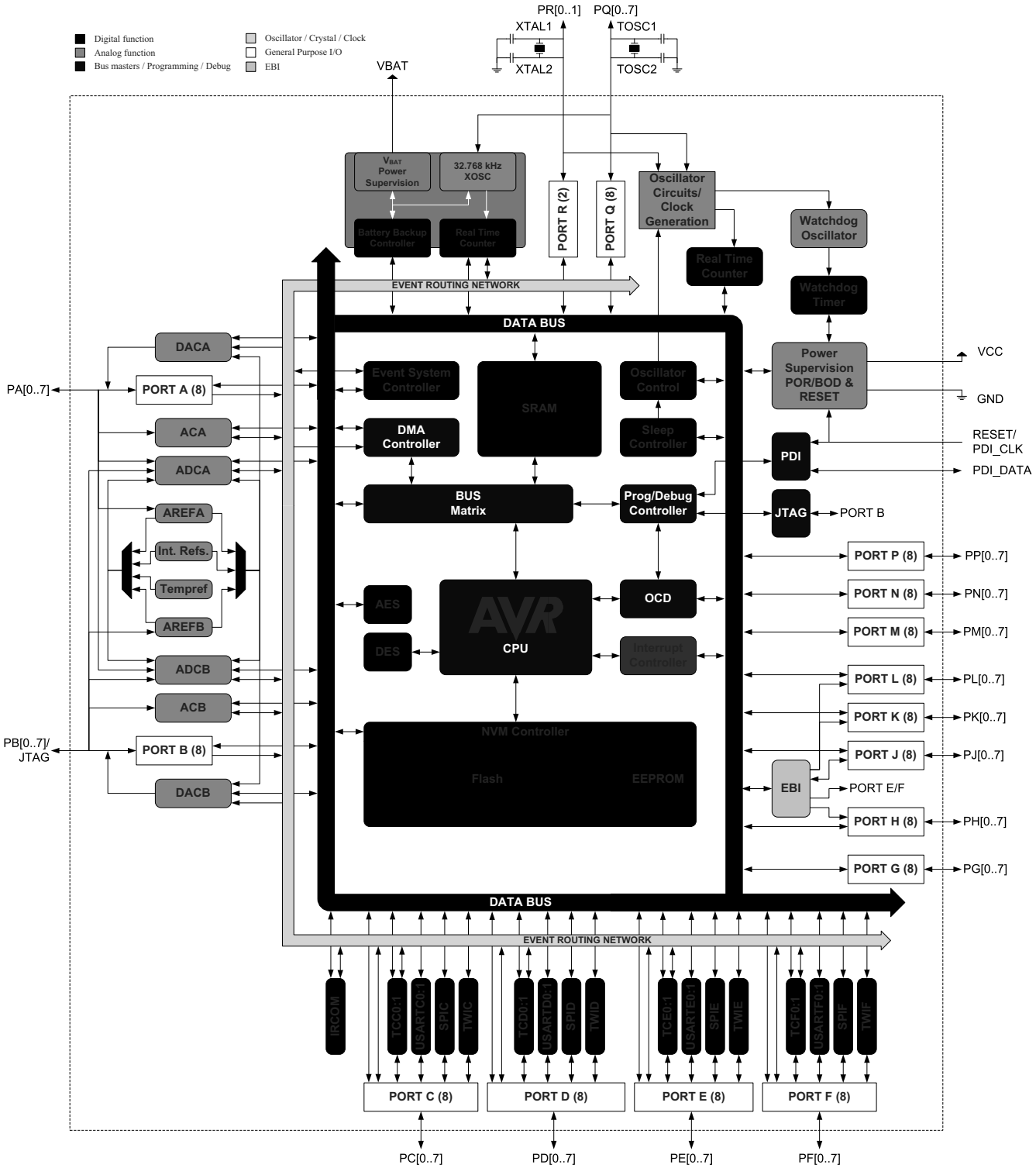
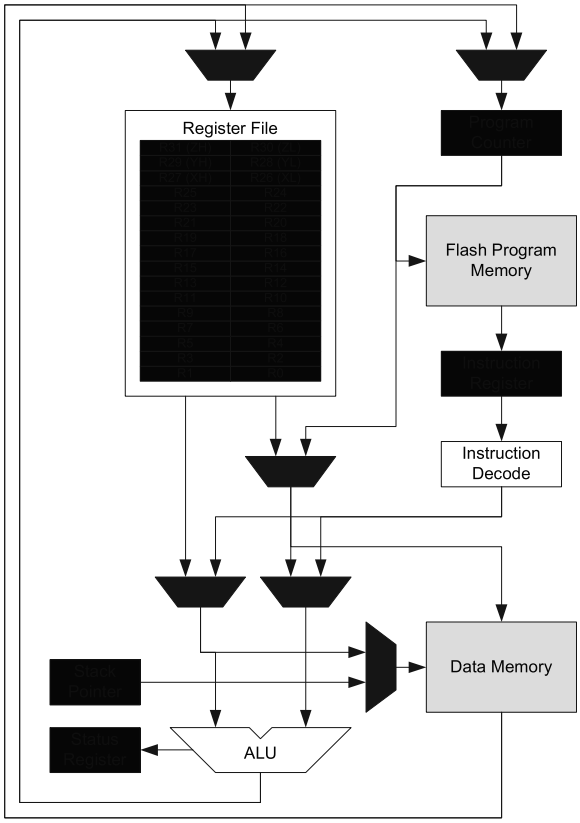


Figure 7-1. Block diagram of the AVR CPU architecture.



The arithmetic logic unit (ALU) supports arithmetic and logic operations between registers or between a constant and a register. Single-register operations can also be executed in the ALU. After an arithmetic operation, the status register is updated to reflect information about the result of the operation.

The ALU is directly connected to the fast-access register file. The 32 x 8-bit general purpose working registers all have single clock cycle access time allowing single-cycle arithmetic logic unit (ALU) operation between registers or between a register and an immediate. Six of the 32 registers can be used as three 16-bit address pointers for program and data space addressing, enabling efficient address calculations.

The memory spaces are linear. The data memory space and the program memory space are two different memory spaces.

The data memory space is divided into I/O registers, SRAM, and external RAM. In addition, the EEPROM can be memory mapped in the data memory.

All I/O status and control registers reside in the lowest 4KB addresses of the data memory. This is referred to as the I/O memory space. The lowest 64 addresses can be accessed directly, or as the data space locations from 0x00 to 0x3F. The rest is the extended I/O memory space, ranging from 0x0040 to 0x0FFF. I/O registers here must be accessed as data space locations using load (LD/LDS/LDD) and store (ST/STS/STD) instructions.

The SRAM holds data. Code execution from SRAM is not supported. It can easily be accessed through the five different addressing modes supported in the AVR architecture. The first SRAM address is 0x2000.

Data addresses 0x1000 to 0x1FFF are reserved for memory mapping of EEPROM.

The program memory is divided in two sections, the application program section and the boot program section. Both sections have dedicated lock bits for write and read/write protection. The SPM instruction that is used for self-programming of the application flash memory must reside in the boot program section. The application section contains an application table section with separate lock bits for write and read/write protection. The application table section can be used for safe storing of nonvolatile data in the program memory.

8.3.4 Production Signature Row

The production signature row is a separate memory section for factory programmed data. It contains calibration data for functions such as oscillators and analog modules. Some of the calibration values will be automatically loaded to the corresponding module or peripheral unit during reset. Other values must be loaded from the signature row and written to the corresponding peripheral registers from software. For details on calibration conditions, refer to “Electrical Characteristics” on page 76.

The production signature row also contains an ID that identifies each microcontroller device type and a serial number for each manufactured device. The serial number consists of the production lot number, wafer number, and wafer coordinates for the device. The device ID for the available devices is shown in Table 8-1.

The production signature row cannot be written or erased, but it can be read from application software and external programmers.

Table 8-1. Device ID bytes.

Device	Device ID bytes		
	Byte 2	Byte 1	Byte 0
ATxmega64A1	4E	96	1E
ATxmega128A1	4C	97	1E

8.3.5 User Signature Row

The user signature row is a separate memory section that is fully accessible (read and write) from application software and external programmers. It is one flash page in size, and is meant for static user parameter storage, such as calibration data, custom serial number, identification numbers, random number seeds, etc. This section is not erased by chip erase commands that erase the flash, and requires a dedicated erase command. This ensures parameter storage during multiple program/erase operations and on-chip debug sessions.

8.4 Fuses and Lock bits

The fuses are used to configure important system functions, and can only be written from an external programmer. The application software can read the fuses. The fuses are used to configure reset sources such as brownout detector and watchdog, startup configuration, JTAG enable, and JTAG user ID.

The lock bits are used to set protection levels for the different flash sections (that is, if read and/or write access should be blocked). Lock bits can be written by external programmers and application software, but only to stricter protection levels. Chip erase is the only way to erase the lock bits. To ensure that flash contents are protected even during chip erase, the lock bits are erased after the rest of the flash memory has been erased.

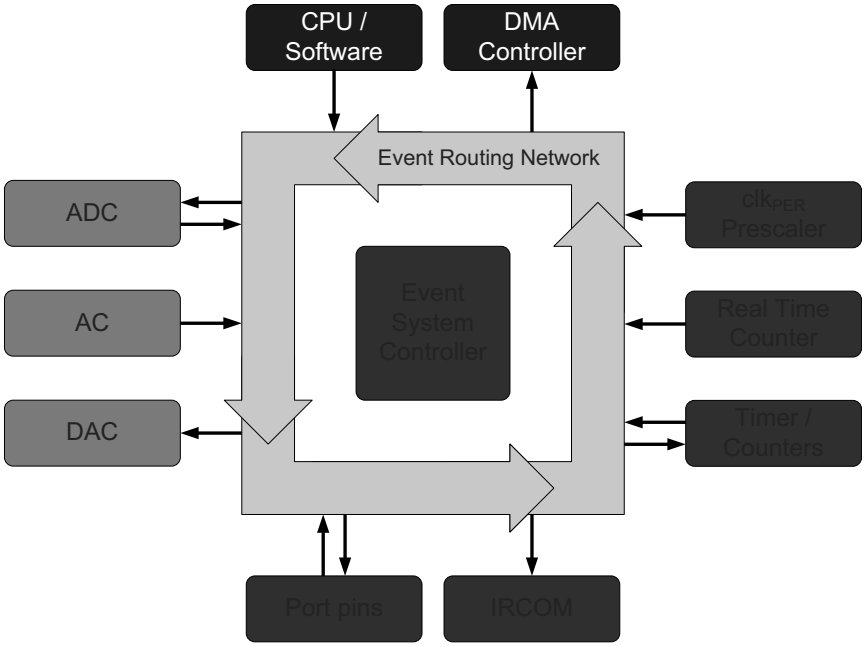
An unprogrammed fuse or lock bit will have the value one, while a programmed fuse or lock bit will have the value zero.

Both fuses and lock bits are reprogrammable like the flash program memory.

8.5 Data Memory

The data memory contains the I/O memory, internal SRAM, optionally memory mapped EEPROM, and external memory if available. The data memory is organized as one continuous memory section, see Figure 8-2 on page 15. To simplify development, I/O Memory, EEPROM and SRAM will always have the same start addresses for all Atmel AVR XMEGA devices. The address space for External Memory will always start at the end of Internal SRAM and end at address 0xFFFFFF.

Figure 10-1. Event system block diagram.



he event routing network consists of eight software-configurable multiplexers that control how events are routed and used. These are called event channels, and allow for up to eight parallel event routing configurations. The maximum routing latency is two peripheral clock cycles. The event system works in both active mode and idle sleep mode.

13. System Control and Reset

13.1 Features

- Multiple reset sources for safe operation and device reset
  - Power-On Reset
  - External Reset
  - Watchdog Reset
  - Brown-Out Reset
  - PDI reset
  - Software reset
- Asynchronous reset
  - No running clock in the device is required for reset
- Reset status register

13.2 Overview

The reset system issues a microcontroller reset and sets the device to its initial state. This is for situations where operation should not start or continue, such as when the microcontroller operates below its power supply rating. If a reset source goes active, the device enters and is kept in reset until all reset sources have released their reset. The I/O pins are immediately tri-stated. The program counter is set to the reset vector location, and all I/O registers are set to their initial values. The SRAM content is kept. However, if the device accesses the SRAM when a reset occurs, the content of the accessed location can not be guaranteed.

After reset is released from all reset sources, the default oscillator is started and calibrated before the device starts running from the reset vector address. By default, this is the lowest program memory address, 0, but it is possible to move the reset vector to the lowest address in the boot section.

The reset functionality is asynchronous, and so no running system clock is required to reset the device. The software reset feature makes it possible to issue a controlled system reset from the user software.

The reset status register has individual status flags for each reset source. It is cleared at power-on reset, and shows which sources have issued a reset since the last power-on.

13.3 Reset Sequence

A reset request from any reset source will immediately reset the device and keep it in reset as long as the request is active. When all reset requests are released, the device will go through three stages before the device starts running again:

- Reset counter delay
- Oscillator startup
- Oscillator calibration

If another reset requests occurs during this process, the reset sequence will start over again.

13.4 Reset Sources

13.4.1 Power-On Reset

TA power-on reset (POR) is generated by an on-chip detection circuit. The POR is activated when the V_{CC} rises and reaches the POR threshold voltage (V_{POT}), and this will start the reset sequence.

The POR is also activated to power down the device properly when the V_{CC} falls and drops below the V_{POT} level.

The V_{POT} level is higher for falling V_{CC} than for rising V_{CC}. Consult the datasheet for POR characteristics data.

Program Address (Base Address)	Source	Interrupt Description
0x01C	TCC0_INT_base	Timer/Counter 0 on port C Interrupt base
0x028	TCC1_INT_base	Timer/Counter 1 on port C Interrupt base
0x030	SPIC_INT_vect	SPI on port C Interrupt vector
0x032	USARTC0_INT_base	USART 0 on port C Interrupt base
0x038	USARTC1_INT_base	USART 1 on port C Interrupt base
0x03E	AES_INT_vect	AES Interrupt vector
0x040	NVM_INT_base	Non-Volatile Memory Interrupt base
0x044	PORTB_INT_base	Port B Interrupt base
0x048	ACB_INT_base	Analog Comparator on Port B Interrupt base
0x04E	ADCB_INT_base	Analog to Digital Converter on Port B Interrupt base
0x056	PORTE_INT_base	Port E Interrupt base
0x05A	TWIE_INT_base	Two-Wire Interface on Port E Interrupt base
0x05E	TCE0_INT_base	Timer/Counter 0 on port E Interrupt base
0x06A	TCE1_INT_base	Timer/Counter 1 on port E Interrupt base
0x072	SPIE_INT_vect	SPI on port E Interrupt vector
0x074	USARTE0_INT_base	USART 0 on port E Interrupt base
0x07A	USARTE1_INT_base	USART 1 on port E Interrupt base
0x080	PORTD_INT_base	Port D Interrupt base
0x084	PORTA_INT_base	Port A Interrupt base
0x088	ACA_INT_base	Analog Comparator on Port A Interrupt base
0x08E	ADCA_INT_base	Analog to Digital Converter on Port A Interrupt base
0x096	TWID_INT_base	Two-Wire Interface on Port D Interrupt base
0x09A	TCD0_INT_base	Timer/Counter 0 on port D Interrupt base
0x0A6	TCD1_INT_base	Timer/Counter 1 on port D Interrupt base
0x0AE	SPID_INT_vector	SPI on port D Interrupt vector
0x0B0	USARTD0_INT_base	USART 0 on port D Interrupt base
0x0B6	USARTD1_INT_base	USART 1 on port D Interrupt base
0x0BC	PORTQ_INT_base	Port Q INT base
0x0C0	PORTH_INT_base	Port H INT base
0x0C4	PORTJ_INT_base	Port J INT base
0x0C8	PORTK_INT_base	Port K INT base
0x0D0	PORTF_INT_base	Port F INT base
0x0D4	TWIF_INT_base	Two-Wire Interface on Port F INT base

Program Address (Base Address)	Source	Interrupt Description
0x0D8	TCF0_INT_base	Timer/Counter 0 on port F Interrupt base
0x0E4	TCF1_INT_base	Timer/Counter 1 on port F Interrupt base
0x0EC	SPIF_INT_vector	SPI ion port F Interrupt base
0x0EE	USARTF0_INT_base	USART 0 on port F Interrupt base
0x0F4	USARTF1_INT_base	USART 1 on port F Interrupt base

It is possible to disable the TWI drivers in the device, and enable a four-wire digital interface for connecting to an external TWI bus driver. This can be used for applications where the device operates from a different VCC voltage than used by the TWI bus.

PORTC, PORTD, PORTE, and PORTF each has one TWI. Notation of these peripherals are TWIC, TWID, TWIE, and TWIF.

28. AC - Analog Comparator

28.1 Features

- Four Analog Comparators
- Selectable propagation delay versus current consumption
- Selectable hysteresis
  - No
  - Small
  - Large
- Analog comparator output available on pin
- Flexible input selection
  - All pins on the port
  - Output from the DAC
  - Bandgap reference voltage
  - A 64-level programmable voltage scaler of the internal VCC voltage
- Interrupt and event generation on:
  - Rising edge
  - Falling edge
  - Toggle
- Window function interrupt and event generation on:
  - Signal above window
  - Signal inside window
  - Signal below window
- Constant current source with configurable output pin selection

28.2 Overview

The analog comparator (AC) compares the voltage levels on two inputs and gives a digital output based on this comparison. The analog comparator may be configured to generate interrupt requests and/or events upon several different combinations of input change.

Two important properties of the analog comparator's dynamic behavior are: hysteresis and propagation delay. Both of these parameters may be adjusted in order to achieve the optimal operation for each application.

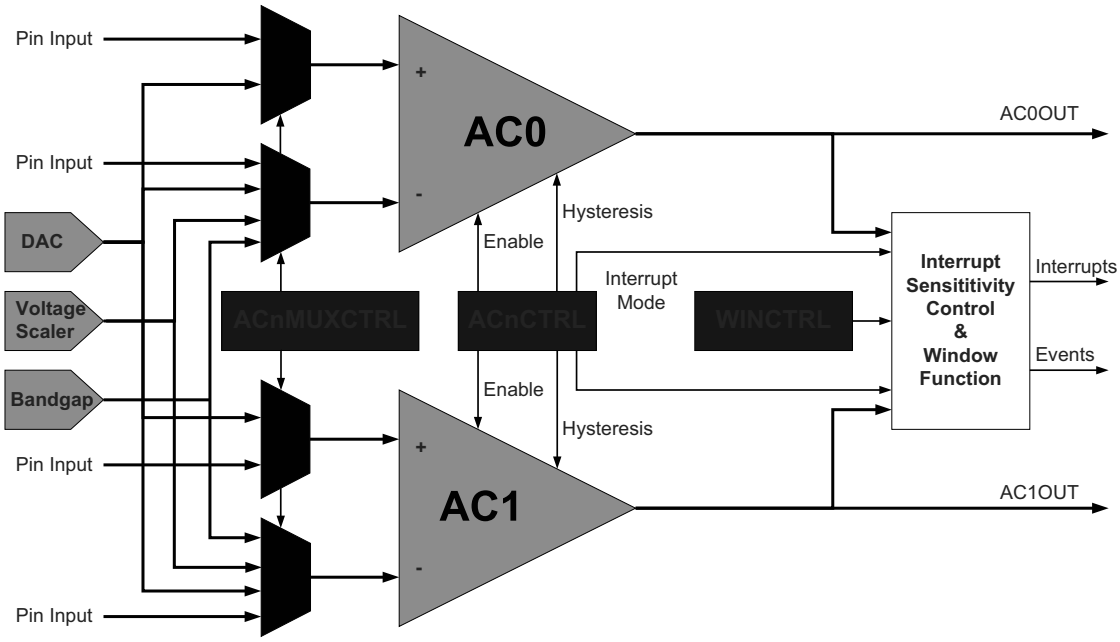
The input selection includes analog port pins, several internal signals, and a 64-level programmable voltage scaler. The analog comparator output state can also be output on a pin for use by external devices.

A constant current source can be enabled and output on a selectable pin. This can be used to replace, for example, external resistors used to charge capacitors in capacitive touch sensing applications.

The analog comparators are always grouped in pairs on each port. These are called analog comparator 0 (AC0) and analog comparator 1 (AC1). They have identical behavior, but separate control registers. Used as pair, they can be set in window mode to compare a signal to a voltage range instead of a voltage level.

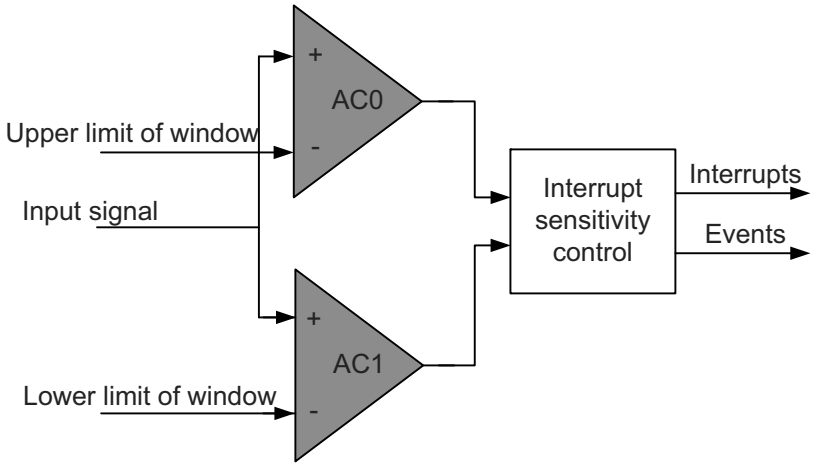
PORTA and PORTB each has one AC pair. Notations are ACA and ACB, respectively.

Figure 28-1. Analog comparator overview



The window function is realized by connecting the external inputs of the two analog comparators in a pair as shown in Figure 28-2.

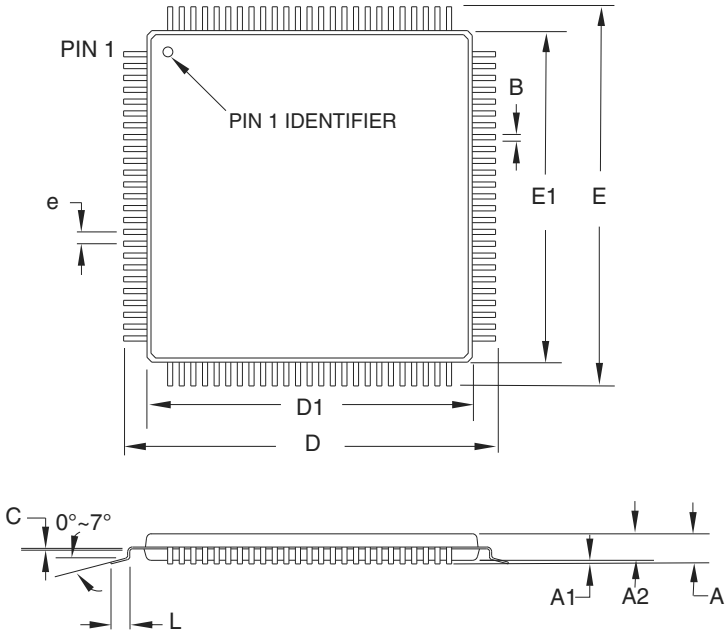
Figure 28-2. Analog comparator window function



Mnemonics	Operands	Description	Operation			Flags	#Clocks
RCALL	k	Relative Call Subroutine	PC	←	PC + k + 1	None	2 / 3(1)
ICALL		Indirect Call to (Z)	PC(15:0) PC(21:16)	← ←	Z, 0	None	2 / 3(1)
EICALL		Extended Indirect Call to (Z)	PC(15:0) PC(21:16)	← ←	Z, EIND	None	3(1)
CALL	k	call Subroutine	PC	←	k	None	3 / 4(1)
RET		Subroutine Return	PC	←	STACK	None	4 / 5(1)
RETI		Interrupt Return	PC	←	STACK	I	4 / 5(1)
CPSE	Rd,Rr	Compare, Skip if Equal	if (Rd = Rr) PC	←	PC + 2 or 3	None	1 / 2 / 3
CP	Rd,Rr	Compare	Rd - Rr			Z,C,N,V,S,H	1
CPC	Rd,Rr	Compare with Carry	Rd - Rr - C			Z,C,N,V,S,H	1
CPI	Rd,K	Compare with Immediate	Rd - K			Z,C,N,V,S,H	1
SBRC	Rr, b	Skip if Bit in Register Cleared	if (Rr(b) = 0) PC	←	PC + 2 or 3	None	1 / 2 / 3
SBRS	Rr, b	Skip if Bit in Register Set	if (Rr(b) = 1) PC	←	PC + 2 or 3	None	1 / 2 / 3
SBIC	A, b	Skip if Bit in I/O Register Cleared	if (I/O(A,b) = 0) PC	←	PC + 2 or 3	None	2 / 3 / 4
SBIS	A, b	Skip if Bit in I/O Register Set	If (I/O(A,b) =1) PC	←	PC + 2 or 3	None	2 / 3 / 4
BRBS	s, k	Branch if Status Flag Set	if (SREG(s) = 1) then PC	←	PC + k + 1	None	1 / 2
BRBC	s, k	Branch if Status Flag Cleared	if (SREG(s) = 0) then PC	←	PC + k + 1	None	1 / 2
BREQ	k	Branch if Equal	if (Z = 1) then PC	←	PC + k + 1	None	1 / 2
BRNE	k	Branch if Not Equal	if (Z = 0) then PC	←	PC + k + 1	None	1 / 2
BRCS	k	Branch if Carry Set	if (C = 1) then PC	←	PC + k + 1	None	1 / 2
BRCC	k	Branch if Carry Cleared	if (C = 0) then PC	←	PC + k + 1	None	1 / 2
BRSH	k	Branch if Same or Higher	if (C = 0) then PC	←	PC + k + 1	None	1 / 2
BRLO	k	Branch if Lower	if (C = 1) then PC	←	PC + k + 1	None	1 / 2
BRMI	k	Branch if Minus	if (N = 1) then PC	←	PC + k + 1	None	1 / 2
BRPL	k	Branch if Plus	if (N = 0) then PC	←	PC + k + 1	None	1 / 2
BRGE	k	Branch if Greater or Equal, Signed	if (N ⊕ V= 0) then PC	←	PC + k + 1	None	1 / 2
BRLT	k	Branch if Less Than, Signed	if (N ⊕ V= 1) then PC	←	PC + k + 1	None	1 / 2
BRHS	k	Branch if Half Carry Flag Set	if (H = 1) then PC	←	PC + k + 1	None	1 / 2
BRHC	k	Branch if Half Carry Flag Cleared	if (H = 0) then PC	←	PC + k + 1	None	1 / 2
BRTS	k	Branch if T Flag Set	if (T = 1) then PC	←	PC + k + 1	None	1 / 2
BRTC	k	Branch if T Flag Cleared	if (T = 0) then PC	←	PC + k + 1	None	1 / 2
BRVS	k	Branch if Overflow Flag is Set	if (V = 1) then PC	←	PC + k + 1	None	1 / 2
BRVC	k	Branch if Overflow Flag is Cleared	if (V = 0) then PC	←	PC + k + 1	None	1 / 2
BRIE	k	Branch if Interrupt Enabled	if (I = 1) then PC	←	PC + k + 1	None	1 / 2
BRID	k	Branch if Interrupt Disabled	if (I = 0) then PC	←	PC + k + 1	None	1 / 2
Data Transfer Instructions							
MOV	Rd, Rr	Copy Register	Rd	←	Rr	None	1
MOVW	Rd, Rr	Copy Register Pair	Rd+1:Rd	←	Rr+1:Rr	None	1

33. Packaging information

33.1 100A



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	15.75	16.00	16.25	
D1	13.90	14.00	14.10	Note 2
E	15.75	16.00	16.25	
E1	13.90	14.00	14.10	Note 2
B	0.17	–	0.27	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.50 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation AED.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.08 mm maximum.

2010-10-20

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**100A,** 100-lead, 14 x 14 mm Body Size, 1.0 mm Body Thickness, 0.5 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	100A	D

Symbol	Parameter	Condition	Min	Typ	Max	Units
	Conversion rate	V_{CC}≥2.0V			2000	ksps
		V_{CC}<2.0V			500	
	Conversion time (propagation delay)	(RES+2)/2+GAIN RES = 8 or 12, GAIN = 0 or 1	5	7	8	ADC_{clk} cycles
	Sampling Time	1/2 ADC_{clk} cycle	0.25			µS
	Conversion range		0		VREF	V
AVCC	Analog Supply Voltage		V_{cc}-0.3		V_{cc}+0.3	V
VREF	Reference voltage		1.0		V_{cc}-0.6	V
	Input bandwidth	V_{CC}≥2.0V			2000	kHz
		V_{CC}<2.0V			500	
INT1V	Internal 1.00V reference			1.00		V
INTVCC	Internal V_{CC}/1.6			V_{CC}/1.6		V
SCALEDVCC	Scaled internal V_{CC}/10 input			V_{CC}/10		V
R_{AREF}	Reference input resistance			>10		MΩ
	Start-up time			12	24	ADC_{clk} cycles
	Internal input sampling speed	Temp. sensor, V_{CC}/10, Bandgap			100	ksps

Table 34-6. ADC gain stage characteristics.

Symbol	Parameter	Condition		Min	Typ	Max	Units
	Gain error	1 to 64 gain			< ±1		%
	Offset error				< ±1		mV
Vrms	Noise level at input	64x gain	VREF = Int. 1V		0.12		mV
			VREF = Ext. 2V		0.06		
	Clock rate	Same as ADC				1000	kHz

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OH}	Output High Voltage GPIO	I_{OH} = -8 mA, V_{CC} = 3.3V	2.6	3		V
		I_{OH} = -6 mA, V_{CC} = 3.0V	2.1	2.2		
		I_{OH} = -2 mA, V_{CC} = 1.8V	1.4	1.6		
I_{IL}	Input Leakage Current I/O pin			<0.001	1	µA
I_{IH}	Input Leakage Current I/O pin			<0.001	1	µA
R_P	I/O pin Pull/Buss keeper Resistor			20		kΩ
R_{RST}	Reset pin Pull-up Resistor			20		kΩ
	Input hysteresis			0.5		V

34.11 POR Characteristics

Table 34-12. Power-on Reset characteristics.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{POT-}	POR threshold voltage falling Vcc			1		V
V_{POT+}	POR threshold voltage rising Vcc			1.4		V

34.12 Reset Characteristics

Table 34-13. Reset characteristics.

Symbol	Parameter	Condition	Min	Typ	Max	Units
	Minimum reset pulse width			90		ns
	Reset threshold voltage	V_{CC} = 2.7 - 3.6V		0.45*V_{CC}		V
		V_{CC} = 1.6 - 2.7V		0.42*V_{CC}		

34.13 Oscillator Characteristics

Table 34-14. Internal 32.768kHz oscillator characteristics.

Symbol	Parameter	Condition	Min	Typ	Max	Units
	Accuracy	T = 85°C, V_{CC} = 3V, After production calibration	-0.5		0.5	%

35.2 Idle Supply Current

Figure 35-3. Idle Supply Current vs. Frequency

f_{SYS} = 1 - 32 MHz, T = 25°C

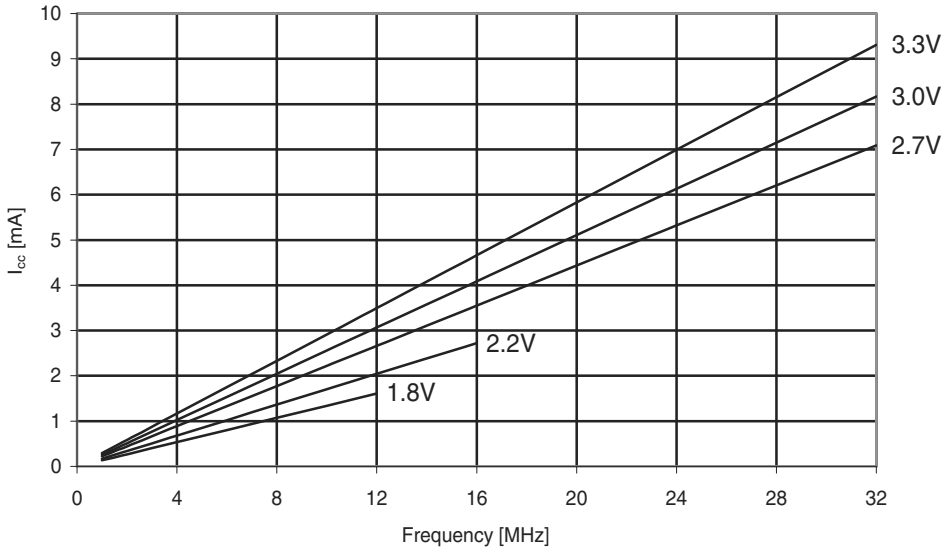


Figure 35-4. Active Supply Current vs. V_{CC}

f_{SYS} = 1.0 MHz

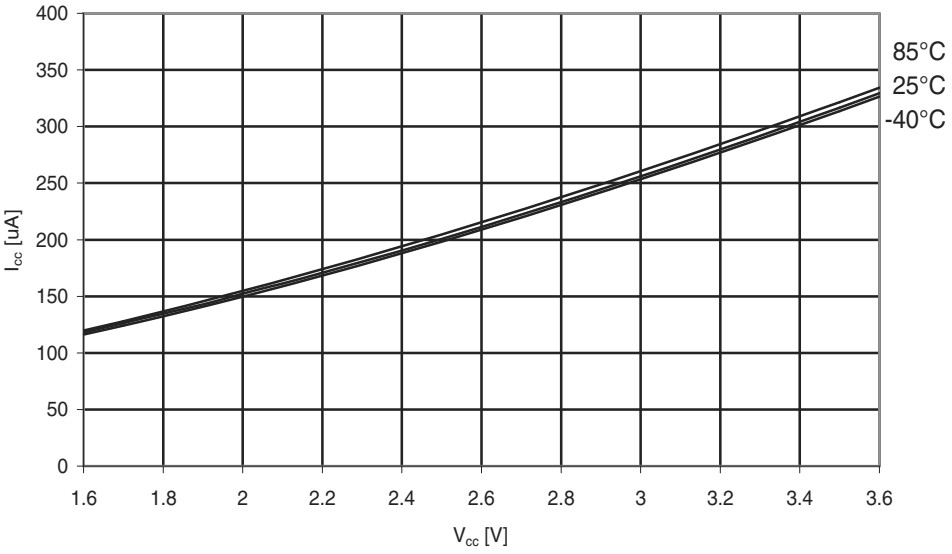


Figure 35-25.Internal 32 MHz Oscillator CalA Calibration Step Size

T = -40 to 85°C, V_{CC} = 3V

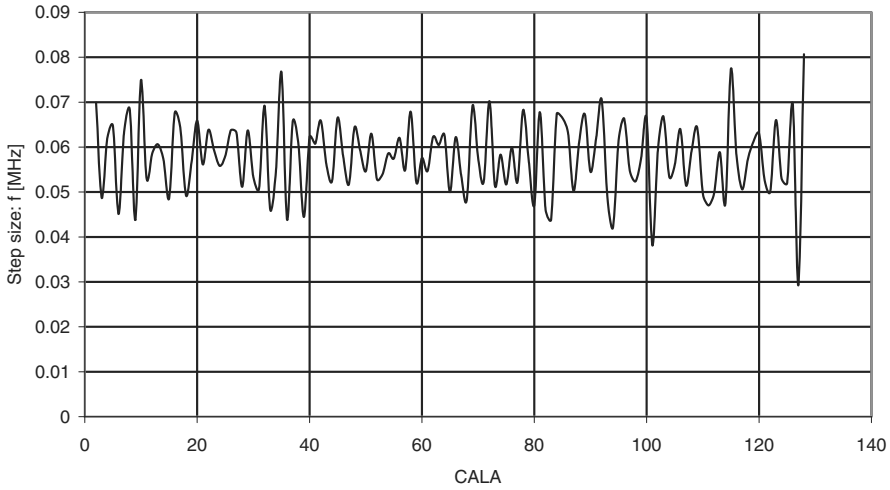
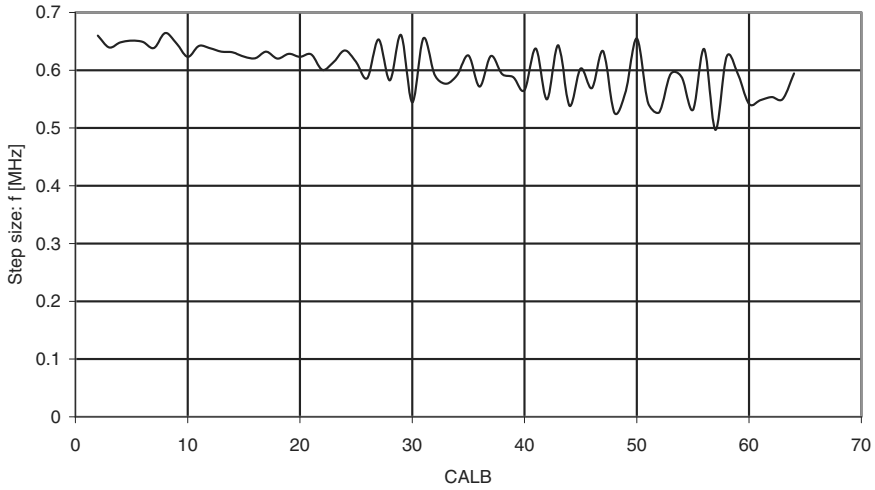


Figure 35-26.Internal 32 MHz Oscillator CalB Calibration Step Size

T = -40 to 85°C, V_{CC} = 3V



6.	Updated “DAC Characteristics” on page 78. Removed DC output impedance.
7.	Fixed typo in “Packaging information” section.
8.	Fixed typo in “Errata” section.

37.5 8067K – 02/2010

1.	Added “PDI Speed vs. VCC” on page 95.

37.6 8067J – 02/2010

1.	Removed JTAG Reset from the datasheet.
2.	Updated “Timer/Counter and AWEX functions” on page 56.
3.	Updated “Alternate Pin Functions” on page 58.
3.	Updated all “Electrical Characteristics” on page 73.
4.	Updated “PAD Characteristics” on page 79.
5.	Changed Internal Oscillator Speed to “Oscillators and Wake-up Time” on page 92.
6.	Updated “Errata” on page 96

37.7 8067I – 04/2009

1.	Updated “Ordering Information” on page 2.
2.	Updated “PAD Characteristics” on page 79.

37.8 8067H – 04/2009

1.	Editorial updates.
2.	Updated “Overview” on page 54.
3.	Updated Table 29-9 on page 54.
4.	Updated “Peripheral Module Address Map” on page 62. IRCOM has address map: 0x08F8.
5.	Updated “Electrical Characteristics” on page 73.
6.	Updated “PAD Characteristics” on page 79.
7.	Updated “Typical Characteristics” on page 82.